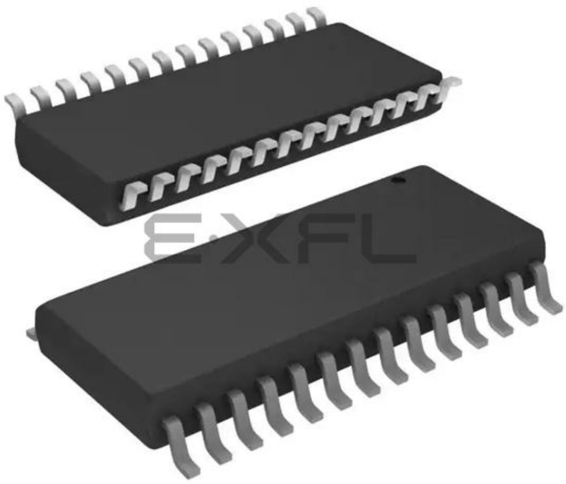

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	21
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep256gp202t-i-so

TABLE 2: dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X MOTOR CONTROL FAMILIES

Device	Page Erase Size (Instructions)	Program Flash Memory (Kbytes)	RAM (Kbytes)	Remappable Peripherals									I2C™	CRC Generator	10-Bit/12-Bit ADC (Channels)	Op Amps/Comparators	CTMU	PTG	I/O Pins	Pins	Packages
				16-Bit/32-Bit Timers	Input Capture	Output Compare	Motor Control PWM(4) (Channels)	Quadrature Encoder Interface	UART	SPI(2)	ECAN™ Technology	External Interrupts(3)									
PIC24EP32MC202	512	32	4	5	4	4	6	1	2	2	—	3	2	1	6	2/3(1)	Yes	Yes	21	28	SPDIP, SOIC, SSOP(5), QFN-S
PIC24EP64MC202	1024	64	8																		
PIC24EP128MC202	1024	128	16																		
PIC24EP256MC202	1024	256	32																		
PIC24EP512MC202	1024	512	48																		
PIC24EP32MC203	512	32	4	5	4	4	6	1	2	2	—	3	2	1	8	3/4	Yes	Yes	25	36	VTLA
PIC24EP64MC203	1024	64	8																		
PIC24EP32MC204	512	32	4	5	4	4	6	1	2	2	—	3	2	1	9	3/4	Yes	Yes	35	44/48	VTLA(5), TQFP, QFN, UQFN
PIC24EP64MC204	1024	64	8																		
PIC24EP128MC204	1024	128	16																		
PIC24EP256MC204	1024	256	32																		
PIC24EP512MC204	1024	512	48																		
PIC24EP64MC206	1024	64	8	5	4	4	6	1	2	2	—	3	2	1	16	3/4	Yes	Yes	53	64	TQFP, QFN
PIC24EP128MC206	1024	128	16																		
PIC24EP256MC206	1024	256	32																		
PIC24EP512MC206	1024	512	48																		
dsPIC33EP32MC202	512	32	4	5	4	4	6	1	2	2	—	3	2	1	6	2/3(1)	Yes	Yes	21	28	SPDIP, SOIC, SSOP(5), QFN-S
dsPIC33EP64MC202	1024	64	8																		
dsPIC33EP128MC202	1024	128	16																		
dsPIC33EP256MC202	1024	256	32																		
dsPIC33EP512MC202	1024	512	48																		
dsPIC33EP32MC203	512	32	4	5	4	4	6	1	2	2	—	3	2	1	8	3/4	Yes	Yes	25	36	VTLA
dsPIC33EP64MC203	1024	64	8																		
dsPIC33EP32MC204	512	32	4	5	4	4	6	1	2	2	—	3	2	1	9	3/4	Yes	Yes	35	44/48	VTLA(5), TQFP, QFN, UQFN
dsPIC33EP64MC204	1024	64	8																		
dsPIC33EP128MC204	1024	128	16																		
dsPIC33EP256MC204	1024	256	32																		
dsPIC33EP512MC204	1024	512	48																		
dsPIC33EP64MC206	1024	64	8	5	4	4	6	1	2	2	—	3	2	1	16	3/4	Yes	Yes	53	64	TQFP, QFN
dsPIC33EP128MC206	1024	128	16																		
dsPIC33EP256MC206	1024	256	32																		
dsPIC33EP512MC206	1024	512	48																		
dsPIC33EP32MC502	512	32	4	5	4	4	6	1	2	2	1	3	2	1	6	2/3(1)	Yes	Yes	21	28	SPDIP, SOIC, SSOP(5), QFN-S
dsPIC33EP64MC502	1024	64	8																		
dsPIC33EP128MC502	1024	128	16																		
dsPIC33EP256MC502	1024	256	32																		
dsPIC33EP512MC502	1024	512	48																		
dsPIC33EP32MC503	512	32	4	5	4	4	6	1	2	2	1	3	2	1	8	3/4	Yes	Yes	25	36	VTLA
dsPIC33EP64MC503	1024	64	8																		

Note 1: On 28-pin devices, Comparator 4 does not have external connections. Refer to **Section 25.0 “Op Amp/Comparator Module”** for details.
2: Only SPI2 is remappable.
3: INT0 is not remappable.
4: Only the PWM Faults are remappable.
5: The SSOP and VTLA packages are not available for devices with 512 Kbytes of memory.

Referenced Sources

This device data sheet is based on the following individual chapters of the *"dsPIC33/PIC24 Family Reference Manual"*. These documents should be considered as the general reference for the operation of a particular module or device feature.

> **Note 1:** To access the documents listed below, browse to the documentation section of the dsPIC33EP64MC506 product page of the Microchip web site (www.microchip.com) or select a family reference manual section from the following list.
>
> In addition to parameters, features and other documentation, the resulting page provides links to the related family reference manual sections.

- **"Introduction"** (DS70573)
- **"CPU"** (DS70359)
- **"Data Memory"** (DS70595)
- **"Program Memory"** (DS70613)
- **"Flash Programming"** (DS70609)
- **"Interrupts"** (DS70600)
- **"Oscillator"** (DS70580)
- **"Reset"** (DS70602)
- **"Watchdog Timer and Power-Saving Modes"** (DS70615)
- **"I/O Ports"** (DS70598)
- **"Timers"** (DS70362)
- **"Input Capture"** (DS70352)
- **"Output Compare"** (DS70358)
- **"High-Speed PWM"** (DS70645)
- **"Quadrature Encoder Interface (QEI)"** (DS70601)
- **"Analog-to-Digital Converter (ADC)"** (DS70621)
- **"UART"** (DS70582)
- **"Serial Peripheral Interface (SPI)"** (DS70569)
- **"Inter-Integrated Circuit (I^2C™)"** (DS70330)
- **"Enhanced Controller Area Network (ECAN™)"** (DS70353)
- **"Direct Memory Access (DMA)"** (DS70348)
- **"CodeGuard™ Security"** (DS70634)
- **"Programming and Diagnostics"** (DS70608)
- **"Op Amp/Comparator"** (DS70357)
- **"Programmable Cyclic Redundancy Check (CRC)"** (DS70346)
- **"Device Configuration"** (DS70618)
- **"Peripheral Trigger Generator (PTG)"** (DS70669)
- **"Charge Time Measurement Unit (CTMU)"** (DS70661)

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REGISTER 3-2: CORCON: CORE CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R-0	R-0	R-0
VAR	—	US1[1]	US0[1]	EDT[1,2]	DL2[1]	DL1[1]	DL0[1]
bit 15							bit 8

R/W-0	R/W-0	R/W-1	R/W-0	R/C-0	R-0	R/W-0	R/W-0
SATA[1]	SATB[1]	SATDW[1]	ACCSAT[1]	IPL3[3]	SFA	RND[1]	IF[1]
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **VAR:** Variable Exception Processing Latency Control bit
1 = Variable exception processing latency is enabled
0 = Fixed exception processing latency is enabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13-12 **US<1:0>:** DSP Multiply Unsigned/Signed Control bits[1]
11 = Reserved
10 = DSP engine multiplies are mixed-sign
01 = DSP engine multiplies are unsigned
00 = DSP engine multiplies are signed

bit 11 **EDT:** Early DO Loop Termination Control bit[1,2]
1 = Terminates executing DO loop at end of current loop iteration
0 = No effect

bit 10-8 **DL<2:0>:** DO Loop Nesting Level Status bits[1]
111 = 7 DO loops are active
•
•
•
001 = 1 DO loop is active
000 = 0 DO loops are active

bit 7 **SATA:** ACCA Saturation Enable bit[1]
1 = Accumulator A saturation is enabled
0 = Accumulator A saturation is disabled

bit 6 **SATB:** ACCB Saturation Enable bit[1]
1 = Accumulator B saturation is enabled
0 = Accumulator B saturation is disabled

bit 5 **SATDW:** Data Space Write from DSP Engine Saturation Enable bit[1]
1 = Data Space write saturation is enabled
0 = Data Space write saturation is disabled

bit 4 **ACCSAT:** Accumulator Saturation Mode Select bit[1]
1 = 9.31 saturation (super saturation)
0 = 1.31 saturation (normal saturation)

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit 3[3]
1 = CPU Interrupt Priority Level is greater than 7
0 = CPU Interrupt Priority Level is 7 or less

Note 1: This bit is available on dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X devices only.
2: This bit is always read as ‘0’.
3: The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU Interrupt Priority Level.

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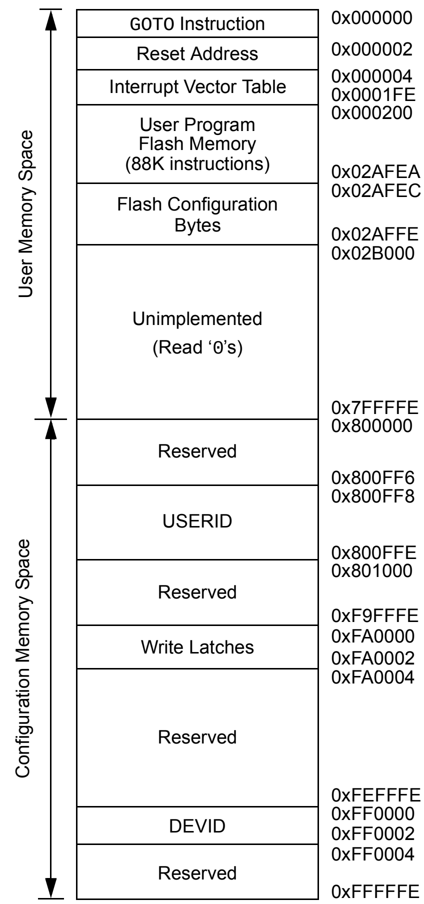
FIGURE 4-4: PROGRAM MEMORY MAP FOR dsPIC33EP256GP50X, dsPIC33EP256MC20X/50X AND PIC24EP256GP/MC20X DEVICES



Note: Memory areas are not shown to scale.

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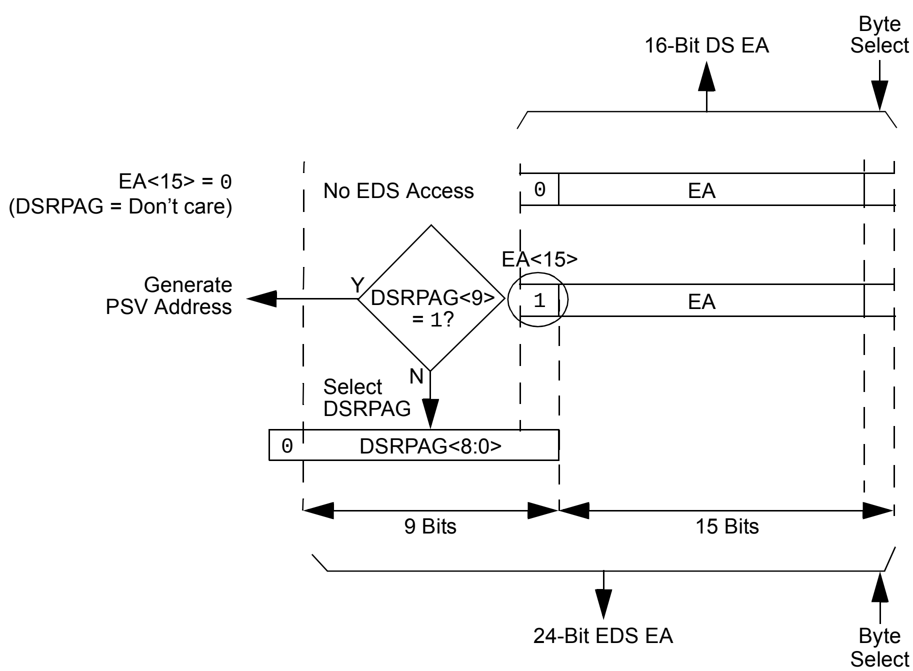
4.4.1 PAGED MEMORY SCHEME

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X architecture extends the available Data Space through a paging scheme, which allows the available Data Space to be accessed using `MOV` instructions in a linear fashion for pre-modified and post-modified Effective Addresses (EA). The upper half of the base Data Space address is used in conjunction with the Data Space Page registers, the 10-bit Read Page register (DSRPAG) or the 9-bit Write Page register (DSWPAG), to form an Extended Data Space (EDS) address or Program Space Visibility (PSV) address. The Data Space Page registers are located in the SFR space.

Construction of the EDS address is shown in Example 4-1. When DSRPAG<9> = `0` and the base address bit, EA<15> = `1`, the DSRPAG<8:0> bits are concatenated onto EA<14:0> to form the 24-bit EDS read address. Similarly, when base address bit, EA<15> = `1`, DSWPAG<8:0> are concatenated onto EA<14:0> to form the 24-bit EDS write address.

EXAMPLE 4-1: EXTENDED DATA SPACE (EDS) READ ADDRESS GENERATION



Note: DS read access when DSRPAG = 0x000 will force an address error trap.

4.8 Interfacing Program and Data Memory Spaces

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X architecture uses a 24-bit-wide Program Space (PS) and a 16-bit-wide Data Space (DS). The architecture is also a modified Harvard scheme, meaning that data can also be present in the Program Space. To use this data successfully, it must be accessed in a way that preserves the alignment of information in both spaces.

Aside from normal execution, the architecture of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices provides two methods by which Program Space can be accessed during operation:

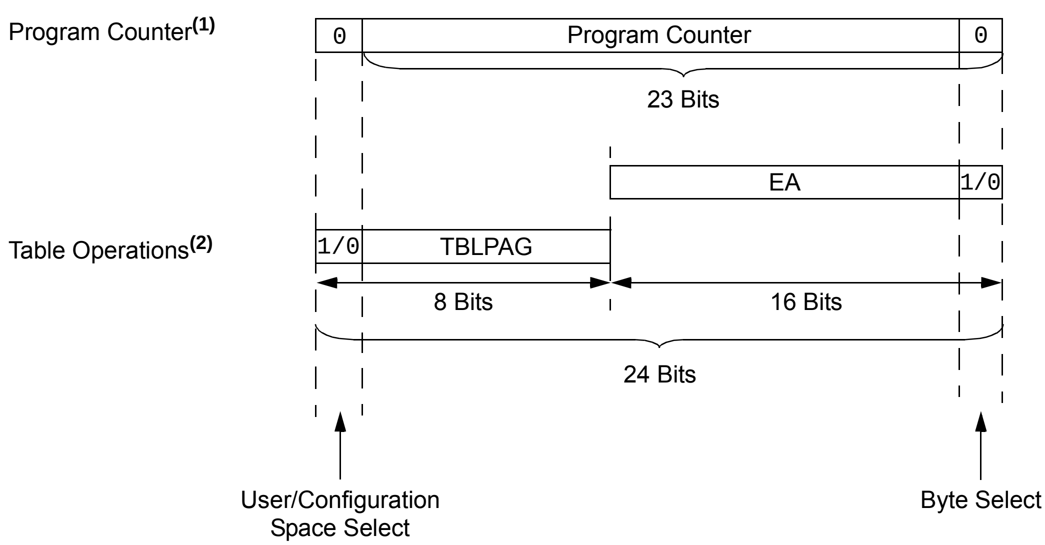
- Using table instructions to access individual bytes or words anywhere in the Program Space
- Remapping a portion of the Program Space into the Data Space (Program Space Visibility)

Table instructions allow an application to read or write to small areas of the program memory. This capability makes the method ideal for accessing data tables that need to be updated periodically. It also allows access to all bytes of the program word. The remapping method allows an application to access a large block of data on a read-only basis, which is ideal for look-ups from a large table of static data. The application can only access the least significant word of the program word.

TABLE 4-65: PROGRAM SPACE ADDRESS CONSTRUCTION

Access Type	Access Space	Program Space Address				
		<23>	<22:16>	<15>	<14:1>	<0>
Instruction Access (Code Execution)	User	0	PC<22:1>			0
		0xx xxxx xxxx xxxx xxxx xxx0				
TBLRD/TBLWT (Byte/Word Read/Write)	User	TBLPAG<7:0>		Data EA<15:0>		
		0xxx xxxx		xxxx xxxx xxxx xxxx		
	Configuration	TBLPAG<7:0>		Data EA<15:0>		
		1xxx xxxx		xxxx xxxx xxxx xxxx		

FIGURE 4-22: DATA ACCESS FROM PROGRAM SPACE ADDRESS GENERATION



Note 1: The Least Significant bit (LSb) of Program Space addresses is always fixed as '0' to maintain word alignment of data in the Program and Data Spaces.

2: Table operations are not required to be word-aligned. Table Read operations are permitted in the configuration memory space.

REGISTER 9-2: CLKDIV: CLOCK DIVISOR REGISTER (CONTINUED)

bit 4-0	**PLLPRE<4:0>:** PLL Phase Detector Input Divider Select bits (also denoted as 'N1', PLL prescaler) 11111 = Input divided by 33 • • • 00001 = Input divided by 3 00000 = Input divided by 2 (default)

Note 1: The DOZE<2:0> bits can only be written to when the DOZEN bit is clear. If DOZEN = 1, any writes to DOZE<2:0> are ignored.

2: This bit is cleared when the ROI bit is set and an interrupt occurs.

3: The DOZEN bit cannot be set if DOZE<2:0> = 000. If DOZE<2:0> = 000, any attempt by user software to set the DOZEN bit is ignored.

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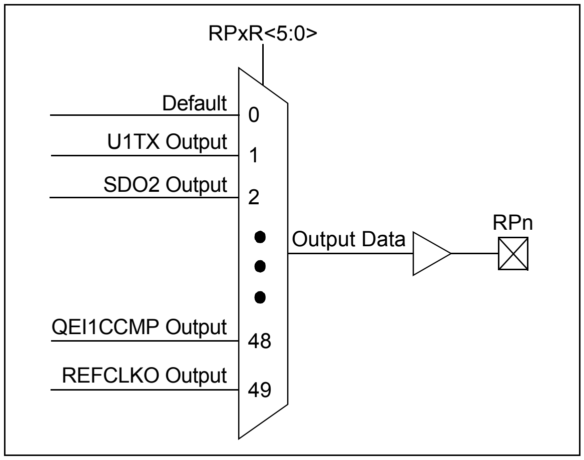
11.4.4.2 Output Mapping

In contrast to inputs, the outputs of the Peripheral Pin Select options are mapped on the basis of the pin. In this case, a control register associated with a particular pin dictates the peripheral output to be mapped. The RPORx registers are used to control output mapping. Like the RPINRx registers, each register contains sets of 6-bit fields, with each set associated with one RPn pin (see Register 11-18 through Register 11-27). The value of the bit field corresponds to one of the peripherals and that peripheral's output is mapped to the pin (see Table 11-3 and Figure 11-3).

A null output is associated with the output register Reset value of '0'. This is done to ensure that remappable outputs remain disconnected from all output pins by default.

FIGURE 11-3: MULTIPLEXING REMAPPABLE OUTPUT FOR RPn



11.4.4.3 Mapping Limitations

The control schema of the peripheral select pins is not limited to a small range of fixed peripheral configurations. There are no mutual or hardware-enforced lockouts between any of the peripheral mapping SFRs. Literally any combination of peripheral mappings across any or all of the RPn pins is possible. This includes both many-to-one and one-to-many mappings of peripheral inputs and outputs to pins. While such mappings may be technically possible from a configuration point of view, they may not be supportable from an electrical point of view.

TABLE 11-3: OUTPUT SELECTION FOR REMAPPABLE PINS (RPn)

Function	RPxR<5:0>	Output Name
Default PORT	000000	RPn tied to Default Pin
U1TX	000001	RPn tied to UART1 Transmit
U2TX	000011	RPn tied to UART2 Transmit
SDO2	001000	RPn tied to SPI2 Data Output
SCK2	001001	RPn tied to SPI2 Clock Output
$\overline{\text{SS2}}$	001010	RPn tied to SPI2 Slave Select
C1TX(2)	001110	RPn tied to CAN1 Transmit
OC1	010000	RPn tied to Output Compare 1 Output
OC2	010001	RPn tied to Output Compare 2 Output
OC3	010010	RPn tied to Output Compare 3 Output
OC4	010011	RPn tied to Output Compare 4 Output
C1OUT	011000	RPn tied to Comparator Output 1
C2OUT	011001	RPn tied to Comparator Output 2
C3OUT	011010	RPn tied to Comparator Output 3
SYNCO1(1)	101101	RPn tied to PWM Primary Time Base Sync Output
QEI1CCMP(1)	101111	RPn tied to QEI 1 Counter Comparator Output
REFCLKO	110001	RPn tied to Reference Clock Output
C4OUT	110010	RPn tied to Comparator Output 4

Note 1: This function is available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.
2: This function is available in dsPIC33EPXXXGP/MC50X devices only.

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REGISTER 21-11: CxFEN1: ECANx ACCEPTANCE FILTER ENABLE REGISTER 1

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
FLTEN15	FLTEN14	FLTEN13	FLTEN12	FLTEN11	FLTEN10	FLTEN9	FLTEN8
bit 15							bit 8

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
FLTEN7	FLTEN6	FLTEN5	FLTEN4	FLTEN3	FLTEN2	FLTEN1	FLTEN0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **FLTEN<15:0>:** Enable Filter n to Accept Messages bits
1 = Enables Filter n
0 = Disables Filter n

REGISTER 21-12: CxBUFPNT1: ECANx FILTER 0-3 BUFFER POINTER REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F3BP<3:0>				F2BP<3:0>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F1BP<3:0>				F0BP<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **F3BP<3:0>:** RX Buffer Mask for Filter 3 bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
•
•
•
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0

bit 11-8 **F2BP<3:0>:** RX Buffer Mask for Filter 2 bits (same values as bits<15:12>)

bit 7-4 **F1BP<3:0>:** RX Buffer Mask for Filter 1 bits (same values as bits<15:12>)

bit 3-0 **F0BP<3:0>:** RX Buffer Mask for Filter 0 bits (same values as bits<15:12>)

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REGISTER 21-19: CxFMSKSEL2: ECANx FILTER 15-8 MASK SELECTION REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F15MSK<1:0>		F14MSK<1:0>		F13MSK<1:0>		F12MSK<1:0>	
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F11MSK<1:0>		F10MSK<1:0>		F9MSK<1:0>		F8MSK<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **F15MSK<1:0>:** Mask Source for Filter 15 bits
11 = Reserved
10 = Acceptance Mask 2 registers contain mask
01 = Acceptance Mask 1 registers contain mask
00 = Acceptance Mask 0 registers contain mask

bit 13-12 **F14MSK<1:0>:** Mask Source for Filter 14 bits (same values as bits<15:14>)

bit 11-10 **F13MSK<1:0>:** Mask Source for Filter 13 bits (same values as bits<15:14>)

bit 9-8 **F12MSK<1:0>:** Mask Source for Filter 12 bits (same values as bits<15:14>)

bit 7-6 **F11MSK<1:0>:** Mask Source for Filter 11 bits (same values as bits<15:14>)

bit 5-4 **F10MSK<1:0>:** Mask Source for Filter 10 bits (same values as bits<15:14>)

bit 3-2 **F9MSK<1:0>:** Mask Source for Filter 9 bits (same values as bits<15:14>)

bit 1-0 **F8MSK<1:0>:** Mask Source for Filter 8 bits (same values as bits<15:14>)

REGISTER 21-22: CxRXFUL1: ECANx RECEIVE BUFFER FULL REGISTER 1

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL15	RXFUL14	RXFUL13	RXFUL12	RXFUL11	RXFUL10	RXFUL9	RXFUL8
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL7	RXFUL6	RXFUL5	RXFUL4	RXFUL3	RXFUL2	RXFUL1	RXFUL0
bit 7							bit 0

Legend:	C = Writable bit, but only ‘0’ can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **RXFUL<15:0>:** Receive Buffer n Full bits
1 = Buffer is full (set by module)
0 = Buffer is empty (cleared by user software)

REGISTER 21-23: CxRXFUL2: ECANx RECEIVE BUFFER FULL REGISTER 2

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL31	RXFUL30	RXFUL29	RXFUL28	RXFUL27	RXFUL26	RXFUL25	RXFUL24
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL23	RXFUL22	RXFUL21	RXFUL20	RXFUL19	RXFUL18	RXFUL17	RXFUL16
bit 7							bit 0

Legend:	C = Writable bit, but only ‘0’ can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **RXFUL<31:16>:** Receive Buffer n Full bits
1 = Buffer is full (set by module)
0 = Buffer is empty (cleared by user software)

21.5 ECAN Message Buffers

ECAN Message Buffers are part of RAM memory. They are not ECAN Special Function Registers. The user application must directly write into the RAM area that is configured for ECAN Message Buffers. The location and size of the buffer area is defined by the user application.

BUFFER 21-1: ECAN™ MESSAGE BUFFER WORD 0

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	SID10	SID9	SID8	SID7	SID6
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
SID5	SID4	SID3	SID2	SID1	SID0	SRR	IDE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12-2 **SID<10:0>:** Standard Identifier bits

bit 1 **SRR:** Substitute Remote Request bit

When IDE = 0:
1 = Message will request remote transmission
0 = Normal message

When IDE = 1:
The SRR bit must be set to ‘1’.

bit 0 **IDE:** Extended Identifier bit

1 = Message will transmit Extended Identifier
0 = Message will transmit Standard Identifier

BUFFER 21-2: ECAN™ MESSAGE BUFFER WORD 1

U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	—	EID17	EID16	EID15	EID14
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
EID13	EID12	EID11	EID10	EID9	EID8	EID7	EID6
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as ‘0’

bit 11-0 **EID<17:6>:** Extended Identifier bits

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22.2 CTMU Control Registers

REGISTER 22-1: CTMUCON1: CTMU CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CTMUEN	—	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN(1)	CTTRIG
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CTMUEN:** CTMU Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **CTMUSIDL:** CTMU Stop in Idle Mode bit
1 = Discontinues module operation when device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **TGEN:** Time Generation Enable bit
1 = Enables edge delay generation
0 = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit
1 = Hardware modules are used to trigger edges (TMRx, CTEDx, etc.)
0 = Software is used to trigger edges (manual set of EDGxSTAT)

bit 10 **EDGSEQEN:** Edge Sequence Enable bit
1 = Edge 1 event must occur before Edge 2 event can occur
0 = No edge sequence is needed

bit 9 **IDISSEN:** Analog Current Source Control bit(1)
1 = Analog current source output is grounded
0 = Analog current source output is not grounded

bit 8 **CTTRIG:** ADC Trigger Control bit
1 = CTMU triggers ADC start of conversion
0 = CTMU does not trigger ADC start of conversion

bit 7-0 **Unimplemented:** Read as ‘0’

Note 1: The ADC module Sample-and-Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitance measurement must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to ‘1’, performs this function. The ADC must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

FIGURE 25-2: COMPARATOR MODULE BLOCK DIAGRAM (MODULE 4)

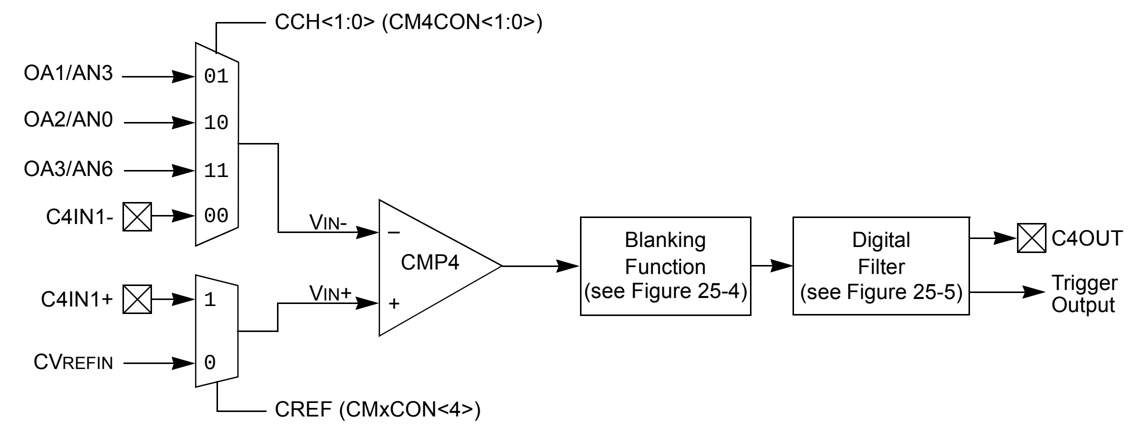
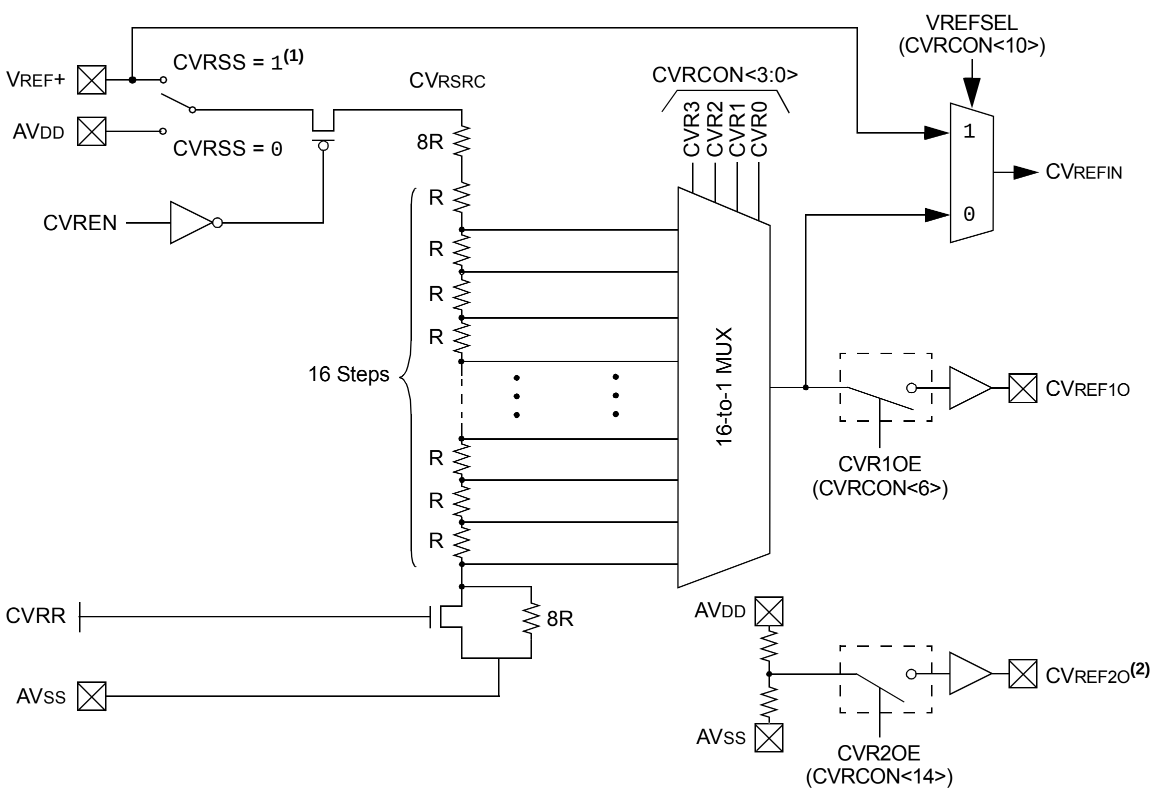


FIGURE 25-3: OP AMP/COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM



Note 1: In order to operate with CVRSS = 1, at least one of the comparator modules must be enabled.
2: This reference is (AVDD + AVSS)/2.

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27.0 SPECIAL FEATURES

> **Note:** This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection and CodeGuard™ Security
- JTAG Boundary Scan Interface
- In-Circuit Serial Programming™ (ICSP™)
- In-Circuit Emulation

27.1 Configuration Bits

In dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices, the Configuration bytes are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored in at the top of the on-chip program memory space, known as the Flash Configuration bytes. Their specific locations are shown in Table 27-1. The configuration data is automatically loaded from the Flash Configuration bytes to the proper Configuration Shadow registers during device Resets.

> **Note:** Configuration data is reloaded on all types of device Resets.

When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration bytes for configuration data in their code for the compiler. This is to make certain that program code is not stored in this address when the code is compiled.

The upper 2 bytes of all Flash Configuration Words in program memory should always be '`1111 1111 1111 1111`'. This makes them appear to be `NOP` instructions in the remote event that their locations are ever executed by accident. Since Configuration bits are not implemented in the corresponding locations, writing '`1`'s to these locations has no effect on device operation.

> **Note:** Performing a page erase operation on the last page of program memory clears the Flash Configuration bytes, enabling code protection as a result. Therefore, users should avoid performing page erase operations on the last page of program memory.

The Configuration Flash bytes map is shown in Table 27-1.

27.6 JTAG Interface

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices implement a JTAG interface, which supports boundary scan device testing. Detailed information on this interface is provided in future revisions of the document.

Note:	Refer to **"Programming and Diagnostics"** (DS70608) in the *"dsPIC33/PIC24 Family Reference Manual"* for further information on usage, configuration and operation of the JTAG interface.

27.7 In-Circuit Serial Programming

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices can be serially programmed while in the end application circuit. This is done with two lines for clock and data, and three other lines for power, ground and the programming sequence. Serial programming allows customers to manufacture boards with unprogrammed devices and then program the device just before shipping the product. Serial programming also allows the most recent firmware or a custom firmware to be programmed. Refer to the *"dsPIC33E/PIC24E Flash Programming Specification for Devices with Volatile Configuration Bits"* (DS70663) for details about In-Circuit Serial Programming (ICSP).

Any of the three pairs of programming clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

27.8 In-Circuit Debugger

When MPLAB® ICD 3 or REAL ICE™ is selected as a debugger, the in-circuit debugging functionality is enabled. This function allows simple debugging functions when used with MPLAB IDE. Debugging functionality is controlled through the PGECx (Emulation/Debug Clock) and PGEDx (Emulation/Debug Data) pin functions.

Any of the three pairs of debugging clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

To use the in-circuit debugger function of the device, the design must implement ICSP connections to $\overline{\text{MCLR}}$, VDD, VSS and the PGECx/PGEDx pin pair. In addition, when the feature is enabled, some of the resources are not available for general use. These resources include the first 80 bytes of data RAM and two I/O pins (PGECx and PGEDx).

27.9 Code Protection and CodeGuard™ Security

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X, and PIC24EPXXXGP/MC20X devices offer basic implementation of CodeGuard Security that supports only General Segment (GS) security. This feature helps protect individual Intellectual Property.

Note:	Refer to **"CodeGuard™ Security"** (DS70634) in the *"dsPIC33/PIC24 Family Reference Manual"* for further information on usage, configuration and operation of CodeGuard Security.

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FIGURE 30-11: TIMERQ (QEI MODULE) EXTERNAL CLOCK TIMING CHARACTERISTICS (dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)

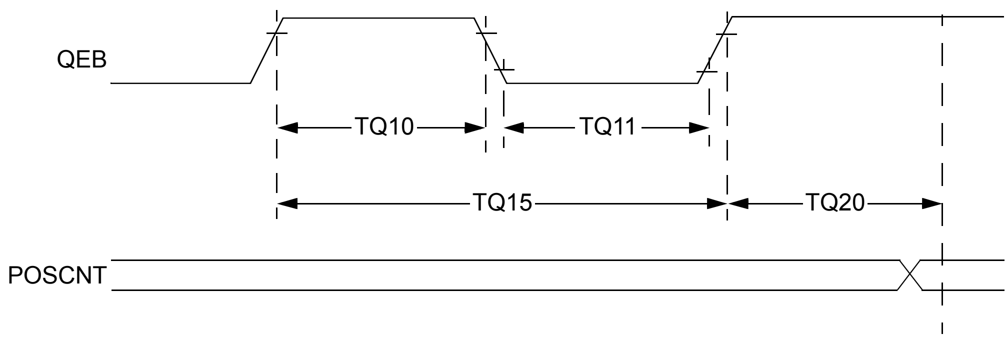
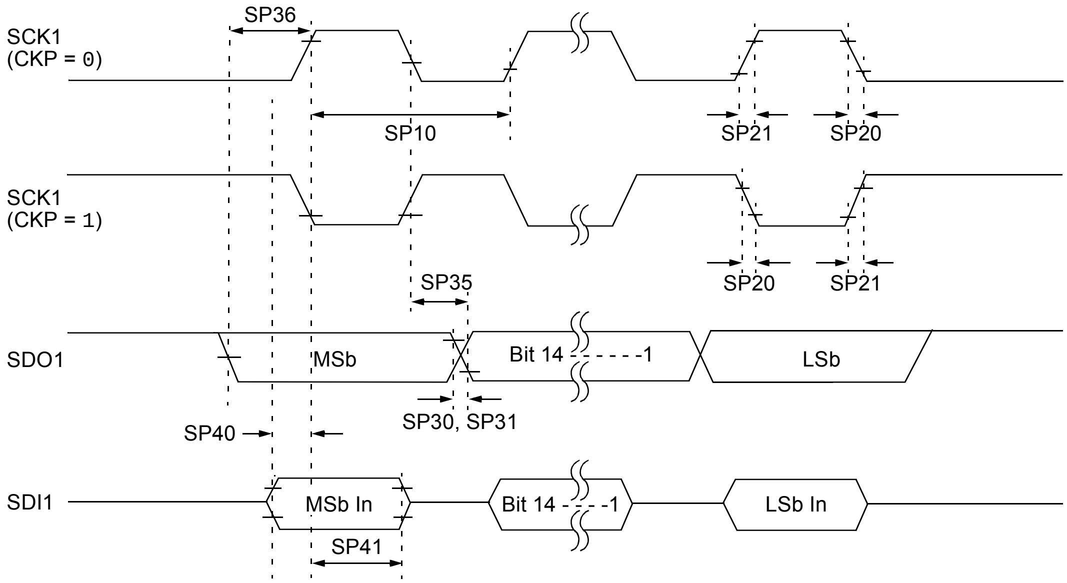


TABLE 30-30: QEI MODULE EXTERNAL CLOCK TIMING REQUIREMENTS (dsPIC33EPXXXMC20X/50X AND PIC24EPXXXMC20X DEVICES ONLY)

AC CHARACTERISTICS				**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**		**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
TQ10	TtQH	TQCK High Time	Synchronous, with prescaler	Greater of 12.5 + 25 or (0.5 TCY/N) + 25	—	—	ns	Must also meet Parameter TQ15
TQ11	TtQL	TQCK Low Time	Synchronous, with prescaler	Greater of 12.5 + 25 or (0.5 TCY/N) + 25	—	—	ns	Must also meet Parameter TQ15
TQ15	TtQP	TQCP Input Period	Synchronous, with prescaler	Greater of 25 + 50 or (1 TCY/N) + 50	—	—	ns	
TQ20	TCKEXTMRL	Delay from External TQCK Clock Edge to Timer Increment		—	1	TCY	—	

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 30-24: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-43: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 1, CKP = x, SMP = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	FscP	Maximum SCK1 Frequency	—	—	10	MHz	**(Note 3)**
SP20	TscF	SCK1 Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP21	TscR	SCK1 Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP30	TdoF	SDO1 Data Output Fall Time	—	—	—	ns	See Parameter DO32 **(Note 4)**
SP31	TdoR	SDO1 Data Output Rise Time	—	—	—	ns	See Parameter DO31 **(Note 4)**
SP35	TscH2doV, TscL2doV	SDO1 Data Output Valid after SCK1 Edge	—	6	20	ns	
SP36	TdoV2sc, TdoV2scL	SDO1 Data Output Setup to First SCK1 Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDI1 Data Input to SCK1 Edge	30	—	—	ns	

Note 1: These parameters are characterized, but are not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCK1 is 100 ns. The clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPI1 pins.

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APPENDIX A: REVISION HISTORY

Revision A (April 2011)

This is the initial released version of the document.

Revision B (July 2011)

This revision includes minor typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in Table A-1.

TABLE A-1: MAJOR SECTION UPDATES

Section Name	Update Description
“High-Performance, 16-bit Digital Signal Controllers and Microcontrollers”	Changed all pin diagrams references of VLAP to TLA.
Section 4.0 “Memory Organization”	Updated the All Resets values for CLKDIV and PLLFBD in the System Control Register Map (see Table 4-35).
Section 5.0 “Flash Program Memory”	Updated “one word” to “two words” in the first paragraph of **Section 5.2 “RTSP Operation”**.
Section 9.0 “Oscillator Configuration”	Updated the PLL Block Diagram (see Figure 9-2). Updated the Oscillator Mode, Fast RC Oscillator (FRC) with divide-by-N and PLL (FRCPLL), by changing (FRCDIVN + PLL) to (FRCPLL). Changed (FRCDIVN + PLL) to (FRCPLL) for COSC<2:0> = `001` and NOSC<2:0> = `001` in the Oscillator Control Register (see Register 9-1). Changed the POR value from 0 to 1 for the DOZE<1:0> bits, from 1 to 0 for the FRCDIV<0> bit, and from 0 to 1 for the PLLPOST<0> bit; Updated the default definitions for the DOZE<2:0> and FRCDIV<2:0> bits and updated all bit definitions for the PLLPOST<1:0> bits in the Clock Divisor Register (see Register 9-2). Changed the POR value from 0 to 1 for the PLLDIV<5:4> bits and updated the default definitions for all PLLDIV<8:0> bits in the PLL Feedback Division Register (see Register 9-2).
Section 22.0 “Charge Time Measurement Unit (CTMU)”	Updated the bit definitions for the IRNG<1:0> bits in the CTMU Current Control Register (see Register 22-3).
Section 25.0 “Op amp/ Comparator Module”	Updated the voltage reference block diagrams (see Figure 25-1 and Figure 25-2).

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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